

Revision History	
Revision	Notes

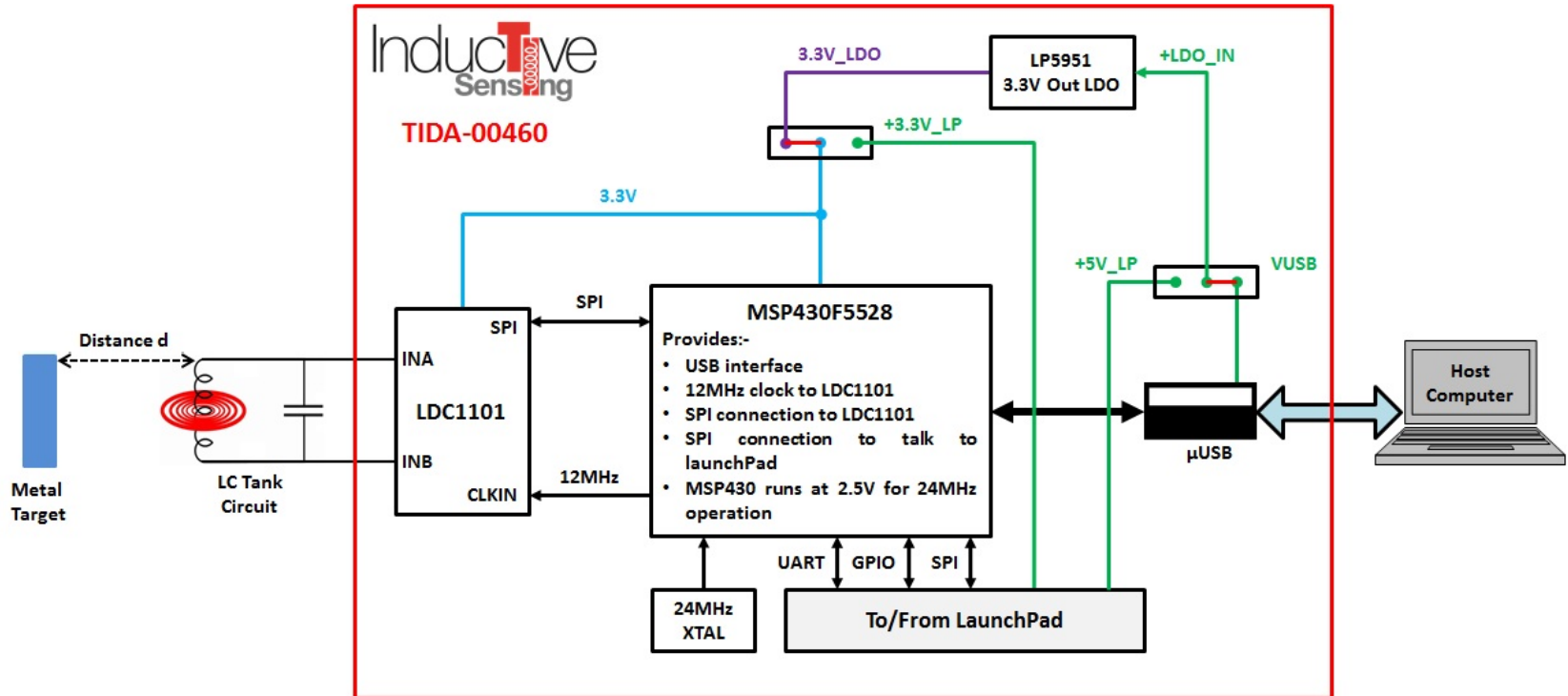
1 2 3 4 5 6

A

B

C

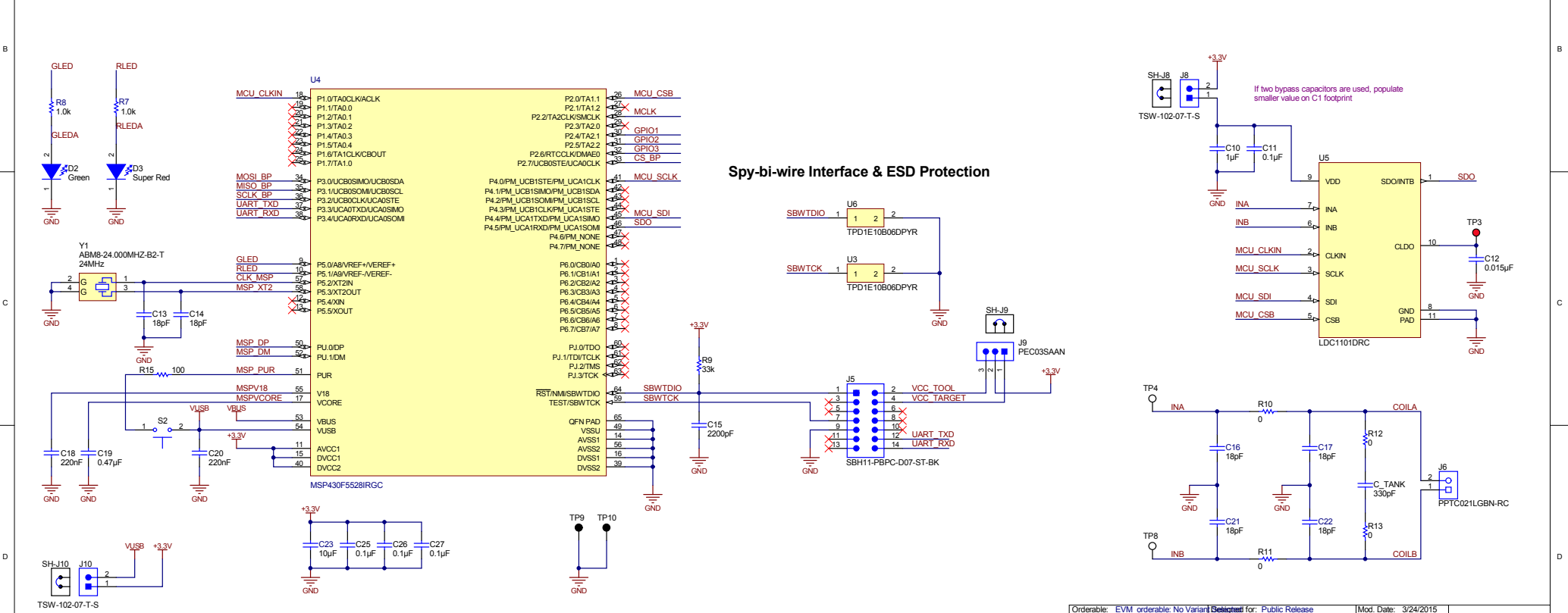
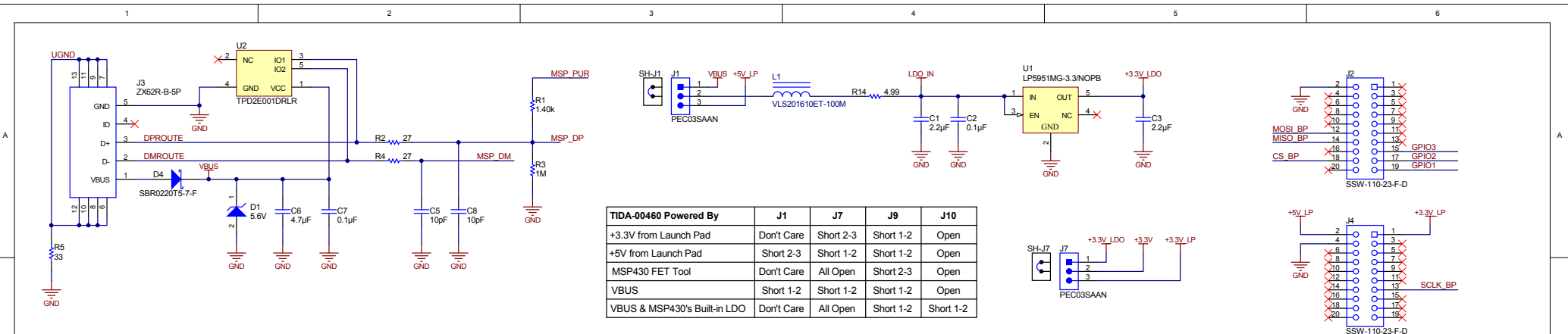
D



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Orderable: EVM	orderable: No Variant	Released for: Public Release	Mod. Date: 6/5/2015
TID #:	N/A	Project Title:	Inductive Linear Position Sensing Booster Pack
Number:	TIDA-00460	Rev:	E1
SVN Rev:	Not in version control	Assembly Variant:	[No Variations]
Drawn By:	Sharad	File:	BoosterPack_40ga_Template_CoverSheet_SchD4jSize: B
Engineer:	Sharad	Contact:	http://www.ti.com/support

1 2 3 4 5 6



TIDA-00460 Powered By	J1	J7	J9	J10
+3.3V from Launch Pad	Don't Care	Short 2-3	Short 1-2	Open
+5V from Launch Pad	Short 2-3	Short 1-2	Short 1-2	Open
MSP430 FET Tool	Don't Care	All Open	Short 2-3	Open
VBUS	Short 1-2	Short 1-2	Short 1-2	Open
VBUS & MSP430's Built-in LDO	Don't Care	All Open	Short 1-2	Short 1-2

Spy-bi-wire Interface & ESD Protection



PCB Number: TIDA-00460
PCB Rev: E1

PCB
LOGO
Texas Instruments

PCB
LOGO
ESD Susceptible

You should delete the nylon screws/standoffs and/or the bump-ons as needed for your design (or substitute other parts from Hardware.IntLib). Bump-ons are cheaper, but provide less clearance.

Deleting anything else from this page may result in your EVM submission being rejected (until you add them back).

Update the Label Text in the Label Table as needed for each Assembly Variant.

You can delete this note too.

Label Table	
Variant	Label Text
001	ChangeMe!
002	ChangeMe!

LBL1
PCB Label
Size: 0.65" x 0.20"

ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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Orderable: EVM orderable: No Variant	Released for: Public Release	Mod. Date: 3/24/2015
TID #: N/A	Project Title: Inductive Linear Position Sensing Booster Pack	
Number: TIDA-00460 Rev: E1	Sheet Title:	
SVN Rev: Not in version control	Assembly Variant: (No Variations)	Sheet: 3 of 3
Drawn By:	File: BoosterPack_40pin_Template_EVM_Hardware_SchDoc_B	
Engineer: Sharad	Contact: http://www.ti.com/support	

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